40 V, 4.0 A, Low V_{CE(sat)} **NPN Transistor**

ON Semiconductor's e²PowerEdge family of low V_{CE(sat)} transistors are miniature surface mount devices featuring ultra low saturation voltage (V_{CE(sat)}) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

• This is a Pb-Free Device

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Мах	Unit	
Collector-Emitter Voltage	V _{CEO}	40	Vdc	
Collector-Base Voltage	V _{CBO}	40	Vdc	
Emitter-Base Voltage	V _{EBO}	6.0	Vdc	
Collector Current - Continuous	۱ _C	2.0	А	
Collector Current - Peak	I _{CM}	4.0	А	
Electrostatic Discharge	ESD	HBM Class 3B MM Class C		

THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Total Device Dissipation $T_A = 25^{\circ}C$	P _D (Note 1)	460	mW
Derate above 25°C		3.7	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$ (Note 1)	270	°C/W
Total Device Dissipation $T_A = 25^{\circ}C$	P _D (Note 2)	540	mW
Derate above 25°C		4.3	mW/°C
Thermal Resistance, Junction-to-Ambient	t R _{θJA} (Note 2) 230		°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

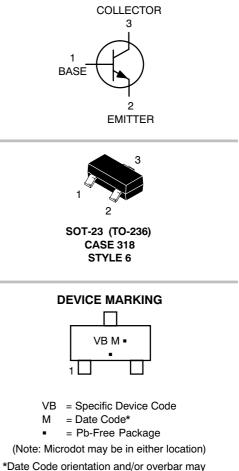
FR-4 @ 100 mm², 1 oz. copper traces.
FR-4 @ 500 mm², 1 oz. copper traces.



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40 VOLTS, 4.0 AMPS NPN LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 44 m Ω



vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS40201LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Мах	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage $(I_C = 10 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	40	-	-	Vdc
Collector-Base Breakdown Voltage $(I_C = 0.1 \text{ mAdc}, I_E = 0)$	V _{(BR)CBO}	40	-	-	Vdc
Emitter-Base Breakdown Voltage $(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	6.0	-	-	Vdc
Collector Cutoff Current ($V_{CB} = 40 \text{ Vdc}, I_E = 0$)	I _{CBO}	-	-	0.1	μAdc
Emitter Cutoff Current (V _{EB} = 6.0 Vdc)	I _{EBO}	-	-	0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 3) ($I_C = 10 \text{ mA}, V_{CE} = 2.0 \text{ V}$) ($I_C = 500 \text{ mA}, V_{CE} = 2.0 \text{ V}$) ($I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}$) ($I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V}$)	h _{FE}	200 200 180 180	- 370 -		
Collector-Emitter Saturation Voltage (Note 3) ($I_C = 0.1 \text{ A}, I_B = 0.010 \text{ A}$) ($I_C = 1.0 \text{ A}, I_B = 0.100 \text{ A}$) ($I_C = 1.0 \text{ A}, I_B = 0.010 \text{ A}$) ($I_C = 2.0 \text{ A}, I_B = 0.200 \text{ A}$)	V _{CE(sat)}	- - -	0.006 0.044 0.085 0.082	0.011 0.060 0.115 0.115	V
Base-Emitter Saturation Voltage (Note 3) ($I_C = 1.0 \text{ A}$, $I_B = 10 \text{ mA}$)	V _{BE(sat)}	-	0.760	0.900	V
Base-Emitter Turn-on Voltage (Note 3) (I _C = 1.0 A, V _{CE} = 2.0 V)	V _{BE(on)}	-	0.760	0.900	V
Cutoff Frequency (I _C = 100 mA, V _{CE} = 5.0 V, f = 100 MHz)	f _T	150	-	-	MHz
Input Capacitance (V _{EB} = 0.5 V, f = 1.0 MHz)	Cibo	-	-	450	pF
Output Capacitance (V_{CB} = 3.0 V, f = 1.0 MHz)	Cobo	-	-	45	pF
SWITCHING CHARACTERISTICS					
Delay (V _{CC} = 30 V, I_C = 750 mA, I_{B1} = 15 mA)	t _d	-	-	100	ns
Rise (V _{CC} = 30 V, I_C = 750 mA, I_{B1} = 15 mA)	t _r	-	-	100	ns
Storage (V _{CC} = 30 V, I_C = 750 mA, I_{B1} = 15 mA)	t _s	-	-	750	ns
Fall (V _{CC} = 30 V, I _C = 750 mA, I _{B1} = 15 mA)	t _f	-	-	110	ns

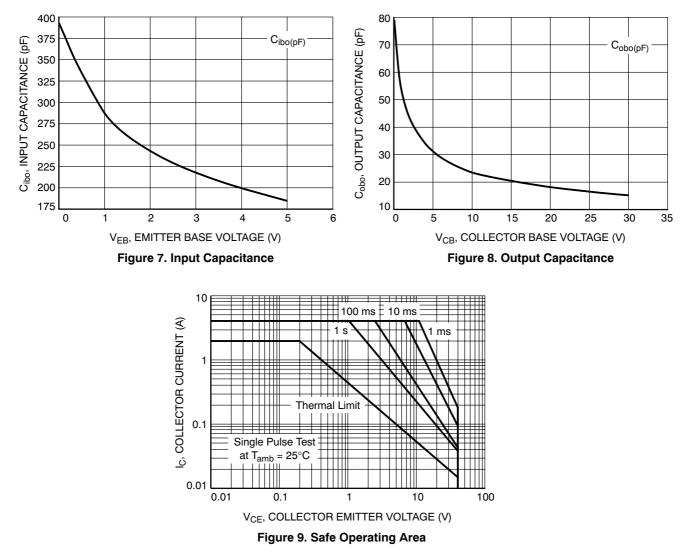
3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle \leq 2%.

0.25 0.35 $I_{\rm C}/I_{\rm B} = 100$ 150°C $I_{\rm C}/I_{\rm B} = 10$ 150°C V_{CE}(sat), COLLECTOR EMITTER SATURATION VOLTAGE (V) 500 51 000 VOLTAGE (V) 51 000 VOLTAGE (V) 52 000 VOLTAGE (V) 53 000 VOLTAGE (V) 53 000 VOLTAGE (V) 54 000 VOLTAGE (V) 54 000 VOLTAGE (V) 55 000 VOLTAGE (V) 56 000 VOLTAGE (V) 56 000 VOLTAGE (V) 57 000 VOLTAGE (V) 50 000 VOLTAGE (V) 5 25°C 25°C -55 °C -55 °C 0 0 0.001 0.01 0.1 10 0.001 0.01 0.1 10 1 1 I_C, COLLECTOR CURRENT (A) I_C, COLLECTOR CURRENT (A) Figure 1. Collector Emitter Saturation Voltage Figure 2. Collector Emitter Saturation Voltage vs. Collector Current vs. Collector Current 800 1.1 1 1 1 1 $I_{\rm C}/I_{\rm B} = 10$ 1.0 700 V_{BE(sat)}, BASE EMITTER SATURATION VOLTAGE (V) h_{FE}, DC CURRENT GAIN 150°C (5.0 V) 0.9 -55 °C 600 150°C (2.0 V) 0.8 500 25°C 0.7 25°C (5.0 V) 400 0.6 25°C (2.0 V) 300 + + 50°C 0.5 -55 °C (5.0 V) 200 0.4 -55 °C (2.0 V) 100 0.3 0.001 0.01 0.1 1 10 0.001 0.01 0.1 1 10 IC, COLLECTOR CURRENT (A) IC, COLLECTOR CURRENT (A) Figure 3. DC Current Gain vs. Collector Figure 4. Base Emitter Saturation Voltage vs. **Collector Current** Current COLLECTOR-EMITTER VOLTAGE (V) 1.0 1.0 I_C = 500 mA V_{CE} = 2.0 V 10 mA 300 mA VBE(on), BASE EMITTER TURN-ON 0.9 -55 °C 0.8 0.8 100 mA 25°C 0.7 VOLTAGE (V) 0.6 0.6 0.5 0.4 150°C 0.4 0.3 0.2 0.2 V_{CE}, (0.1 0 0.001 0.1 0.01 0.1 10 0.01 100 1 10 1 I_C, COLLECTOR CURRENT (A) IB, BASE CURRENT (mA)

TYPICAL CHARACTERISTICS

Figure 5. Base Emitter Turn-On Voltage vs. Collector Current

TYPICAL CHARACTERISTICS



PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**

NOTES

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08. 4.

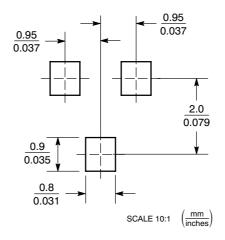
	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
Е	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
Г	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
He	2 10	2 40	2 64	0.083	0.001	0 104



PIN 1. BASE 2. FMITTER

3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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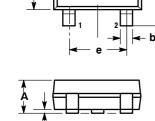
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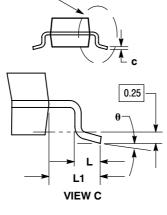
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